

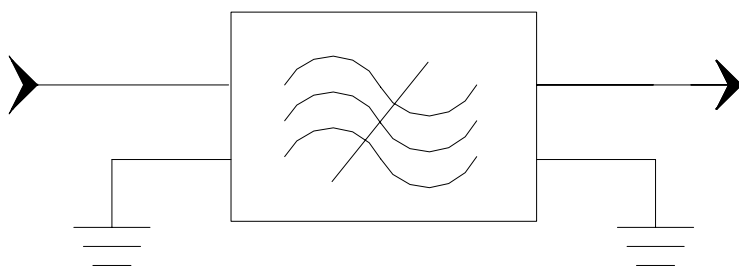
Specifications

Parameter	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	84.72	84.8	84.88
Insertion Loss	dB		17.5	19
1dB Bandwidth	MHz	7.1	7.2	
3 dB Bandwidth	MHz	7.4	7.78	
40 dB Bandwidth	MHz		9.63	9.7
Group delay Variation($f_0 \pm 2.84\text{MHz}$)	nsec		30	100
Phase Linearity ($f_0 \pm 2.84\text{MHz}$)	degree		3	5
Passband Variation	dB		1	1.2
Absolute Delay	usec		2	2.2
Ultimate Rejection($f_0 \pm 15\text{MHz}$)	dB	54	60	
Substrate Material			YZ	
Ambient Temperature	°C		25	
Package Size		DIP2712 (27.0x12.8x4.7mm ³)		

Notes:

1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance show

Matching Configuration



Source/Load Impedance=50 ohm

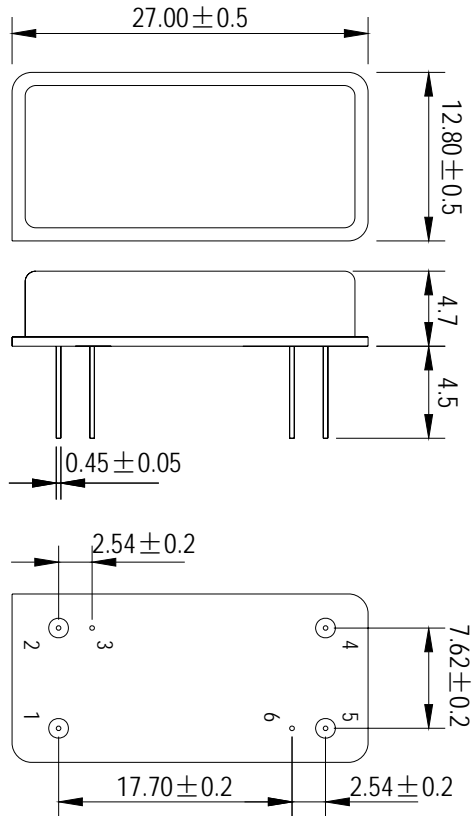
Notes - Component values may change depending on board layout.



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Package Dimension



Pin 1: input
Pin 5: output
Others: Grounded



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